

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00635	1.57	0.09577
	Doped silicon	Silicon (Si)	7440-21-3	0.39834	98.43	6.00423
Subtotal				0.40469	100	6.1
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32177	100.0	4.85
	Subtotal				0.32177	100
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00975	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.0065	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00975	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03574	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.43261	99.81	488.8594
	Subtotal				32.49435	100
Mould Compound	Additive	Cristobalite	14464-46-1	0.3312	0.5	4.9922
	Filler	Silica fused	60676-86-0	54.31675	82.0	818.7208
	Polymer	Phenolic resin		3.312	5.0	49.922
	Flame retardant	Metal hydroxide		2.6496	4.0	39.9376
	Pigment	Carbon black	1333-86-4	0.3312	0.5	4.9922
	Polymer	Epoxy resin system		5.2992	8.0	79.8752
	Subtotal				66.23995	100
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.02601	10.0	0.39199
	Silver alloy	Silver (Ag)	7440-22-4	0.0052	2.0	0.0784
	Lead alloy	Lead (Pb)	7439-92-1	0.22885	88.0	3.44949
	Subtotal				0.26006	100
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.27919	100.0	4.20829
	Subtotal				0.27919	100
Total				100.00001	100	1507.30818

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